PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
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EPAS ID: PAT2690630

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
IL KWON SHIM	12/20/2013
KYUNG MOON KIM	12/23/2013
HEEJO CHI	12/23/2013
JUNMO KOO	12/20/2013
BARTHOLOMEW LIAO	12/20/2013
ZIGMUND RAMIREZ CAMACHO	12/20/2013

RECEIVING PARTY DATA

Name:	STATS ChipPAC Ltd.
Street Address:	10 Ang Mo Kio Street 65
Internal Address:	#05-17/20 Techpoint
City:	Singapore
State/Country:	SINGAPORE
Postal Code:	569059

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14140829

CORRESPONDENCE DATA

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Correspondent Name:	ISHIMARU & ASSOCIATES LLP
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ATTORNEY DOCKET NUMBER:	27-904

NAME OF SUBMITTER:	MIKIO ISHIMARU
Signature:	/Mikio Ishimaru/
Date:	01/21/2014
Total Attachments: 4 source=27-904_Assignment#page1.tif source=27-904_Assignment#page2.tif source=27-904_Assignment#page3.tif source=27-904_Assignment#page4.tif	

ASSIGNMENT

WHEREAS, the undersigned (hereinafter termed Assignor(s)) has/have invented certain new and useful improvements in

INTEGRATED CIRCUIT PACKAGING SYSTEM WITH UNDER BUMP METALLIZATION AND METHOD OF MANUFACTURE THEREOF

for which a United States patent application has been executed on or before the date of this assignment;

WHEREAS, STATS ChipPAC Ltd., a Corporation of the Republic of Singapore, having a place of business at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, Republic of Singapore (hereinafter termed Assignee), is desirous of acquiring the entire right, title and interest in and to said application and said invention and improvements thereon, and in and to Letters Patents thereon when granted in the United States and foreign countries;

NOW, THEREFORE, for good and valuable consideration received by said Assignor(s) from said Assignee(s), the receipt of which is hereby acknowledged by said Assignor(s):

1. Said Assignor(s) does hereby sell, assign, transfer and convey unto said Assignee(s), the entire right, title and interest in and to said application and said invention and in and to any and all improvements on said invention and in and to any and all improvements on said invention heretofore or hereafter made or acquired by said Assignor(s); and in and to any and all Letters Patent on said invention and/or said improvements that may be granted in the United States or any foreign country, including each and every Letters Patent granted on any application which is a division, continuation, substitution, renewal, or continuation-in-part of any said application, and in and to each and every reissue or extension of said Letters Patent.

2. Said Assignor(s) hereby covenants and agrees to cooperate with said Assignee(s) where said Assignee(s) may enjoy to the fullest extent the right, title and interest herein conveyed. Such cooperation shall include (a) prompt execution of all papers (prepared at the expense of Assignee(s)) which are deemed necessary or desirable by Assignee(s) to perfect in it the right, title and interest herein conveyed, (b) prompt execution of all petitions, oaths, specifications or other papers (prepared at the expense of Assignee(s)) which are deemed necessary or desirable by Assignee(s) for prosecuting said application, for filing and prosecuting divisional, continuation, substitution, renewal, continuation-in-part, or additional applications in the United States and/or foreign countries covering said invention and/or said improvements, for filing and prosecuting applications for reissuance of letters patent included herein, or for interference proceedings involving said invention and/or said improvements and (c) prompt assistance and cooperation in the prosecution of interference proceedings involving said invention and/or said improvements and in the adjudication of said Letters Patent, particularly by the disclosure of facts and the production of evidence relating to said invention and/or said improvements, provided the expenses which may be incurred by said Assignor(s) in lending such assistance and cooperation shall be paid by the Assignee(s).

3. The terms, covenants and conditions of this assignment shall inure to the benefit of said Assignee(s), its successors, assigns and/or other legal representatives and shall be binding upon said Assignor(s), his/her heirs, legal representatives and assigns.

4. Said Assignor(s) hereby warrants and represents that he/she has not entered into any assignment, contract or understanding in conflict herewith.

5. Said Assignor(s) hereby authorizes and requests the attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow:

Serial Number: 14/140,829 Filing Date: December 26, 2013.

The said Assignor has executed and delivered this instrument on the date set forth below.

20/12/13

Il Kwon Shim Date

The said Assignor has executed and delivered this instrument on the date set forth below.

Kyung Moon Kim Date

The said Assignor has executed and delivered this instrument on the date set forth below.

HeeJo Chi Date

4. Said Assignor(s) hereby warrants and represents that he/she has not entered into any assignment, contract or understanding in conflict herewith.

5. Said Assignor(s) hereby authorizes and requests the attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow:

Serial Number: ____________________ Filing Date: ____________________.

The said Assignor has executed and delivered this instrument on the date set forth below.

____________________ ____________________

Il Kwon Shim Date

The said Assignor has executed and delivered this instrument on the date set forth below.

____________________ 23 DEC 2013

Kyung Moon Kim Date

The said Assignor has executed and delivered this instrument on the date set forth below.

____________________ 23 DEC 2013

HeeJo Chi Date

The said Assignor has executed and delivered this instrument on the date set forth below.

20 Dec. 2013

JunMo Koo — Date

The said Assignor has executed and delivered this instrument on the date set forth below.

20 Dec. 2013

Bartholomew Liao — Date

The said Assignor has executed and delivered this instrument on the date set forth below.

20 DEC 2013

Zigmund Ramirez Camacho — Date